

N and P Channel Enhancement Mode Power MOSFET

Description

The G100C04D52 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

- NMOS

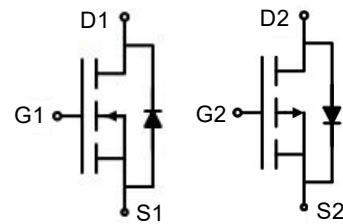
V_{DS}	40V
I_D (at $V_{GS} = 10V$)	40A
$R_{DS(ON)}$ (at $V_{GS} = 10V$)	< 9mΩ
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$)	< 12mΩ
- 100% Avalanche Tested
- RoHS Compliant

- PMOS

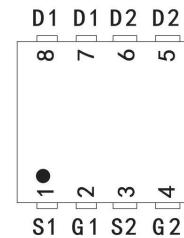
V_{DS}	-40V
I_D (at $V_{GS} = -10V$)	-24A
$R_{DS(ON)}$ (at $V_{GS} = -10V$)	< 16mΩ
$R_{DS(ON)}$ (at $V_{GS} = -4.5V$)	< 20mΩ
- 100% Avalanche Tested
- RoHS Compliant

Application

- Power switch
- DC/DC converters



Schematic diagram



pin assignment



DFN5X6-8L Dual

Ordering Information

Device	Package	Marking	Packaging
G100C04D52	DFN5*6-8L Dual	G100C04	5000pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	NMOS	PMOS	Unit
Drain-Source Voltage	V_{DS}	40	-40	V
Continuous Drain Current	I_D	40	-24	A
Pulsed Drain Current (note1)	I_{DM}	200	-96	A
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Power Dissipation	P_D	65	50	W
Single pulse avalanche energy (note2)	E_{AS}	81	81	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	-55 To 150	°C

Thermal Resistance

Parameter	Symbol	NMOS	PMOS	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	40	50	°C/W
Maximum Junction-to-Case	R_{thJC}	1.9	2.5	°C/W

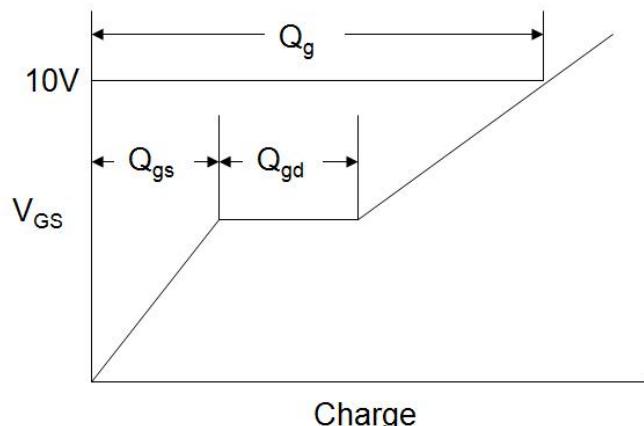
NMOS Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.8	2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$	--	7	9	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$	--	9	12	
Forward Transconductance	g_{FS}	$V_{\text{GS}} = 5\text{V}, I_D = 12\text{A}$	--	22	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 20\text{V}, f = 1.0\text{MHz}$	--	2213	--	pF
Output Capacitance	C_{oss}		--	173	--	
Reverse Transfer Capacitance	C_{rss}		--	156	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 20\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}$	--	29	--	nC
Gate-Source Charge	Q_{gs}		--	4.5	--	
Gate-Drain Charge	Q_{gd}		--	6.5	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 20\text{V}, I_D = 30\text{A}, R_G = 3\Omega$	--	17	--	ns
Turn-on Rise Time	t_r		--	6.5	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	30	--	
Turn-off Fall Time	t_f		--	17	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	40	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 30\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 30\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A/us}$	--	26	--	nC
Reverse Recovery Time	T_{rr}		--	29	--	ns

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=40\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
3. Identical low side and high side switch with identical R_G

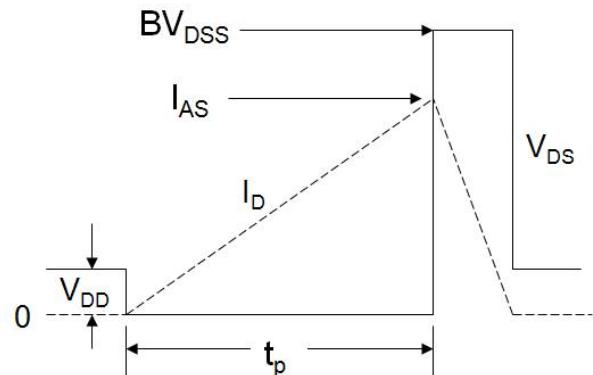
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



NMOS Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

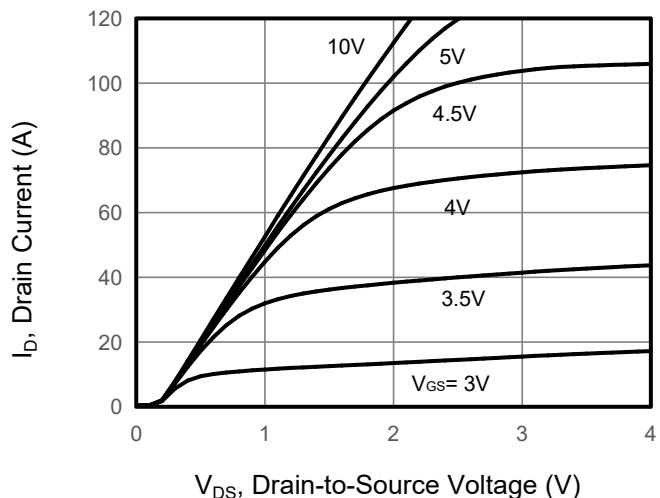


Figure 2. Transfer Characteristics

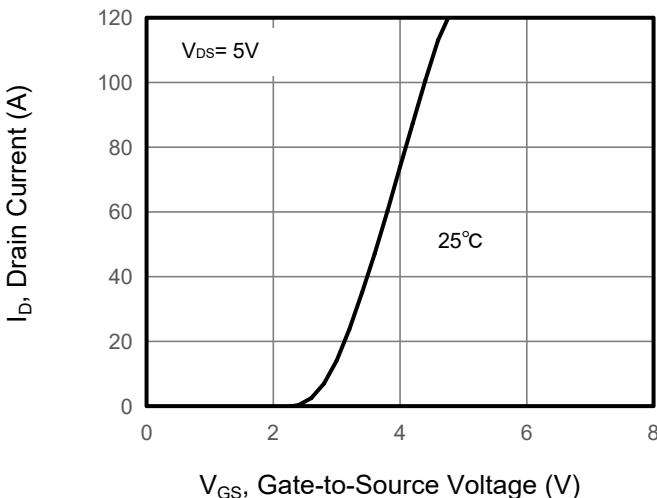


Figure 3. Drain Source On Resistance

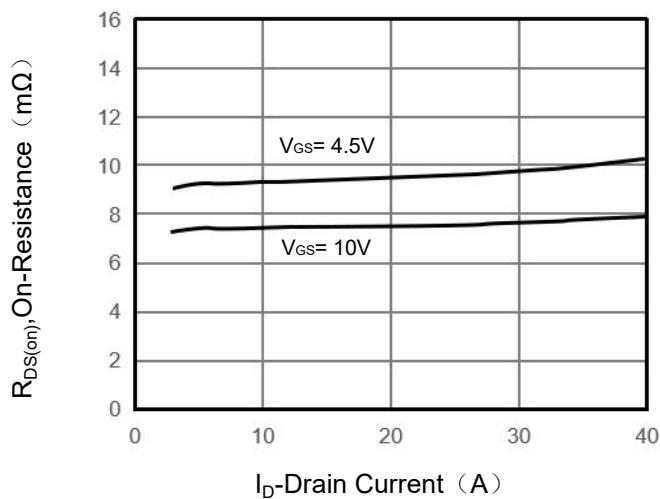


Figure 4. Gate Charge

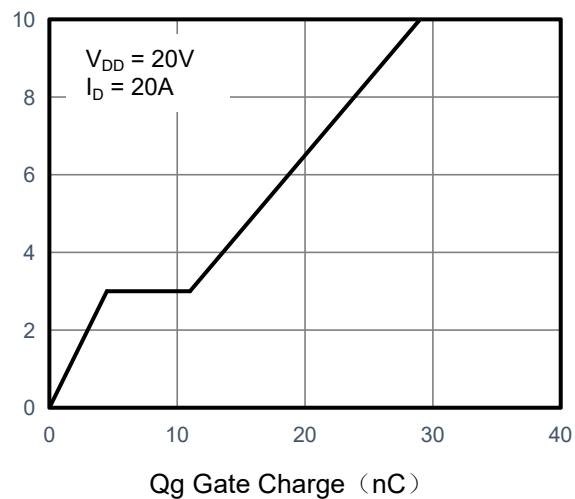


Figure 5. Capacitance

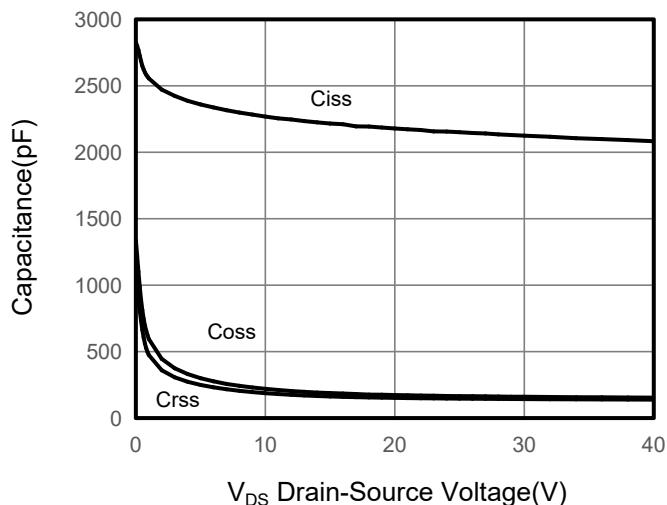
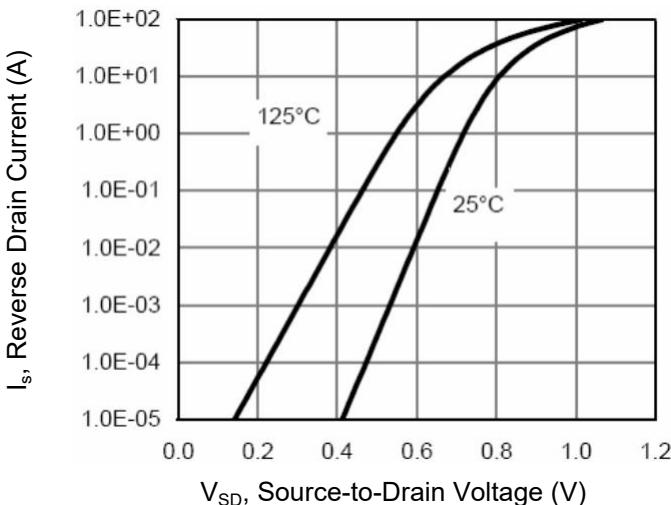


Figure 6. Source-Drain Diode Forward



NMOS Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

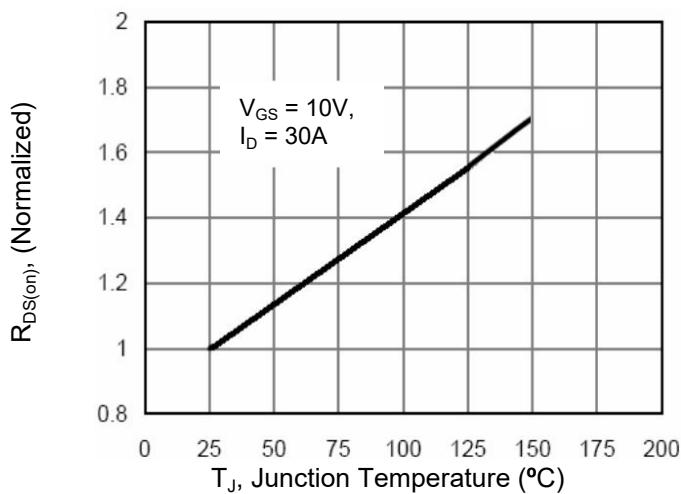


Figure 8. Safe Operation Area

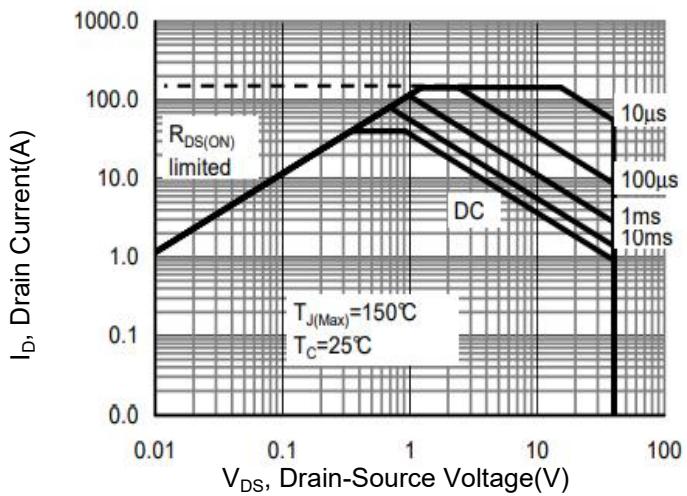
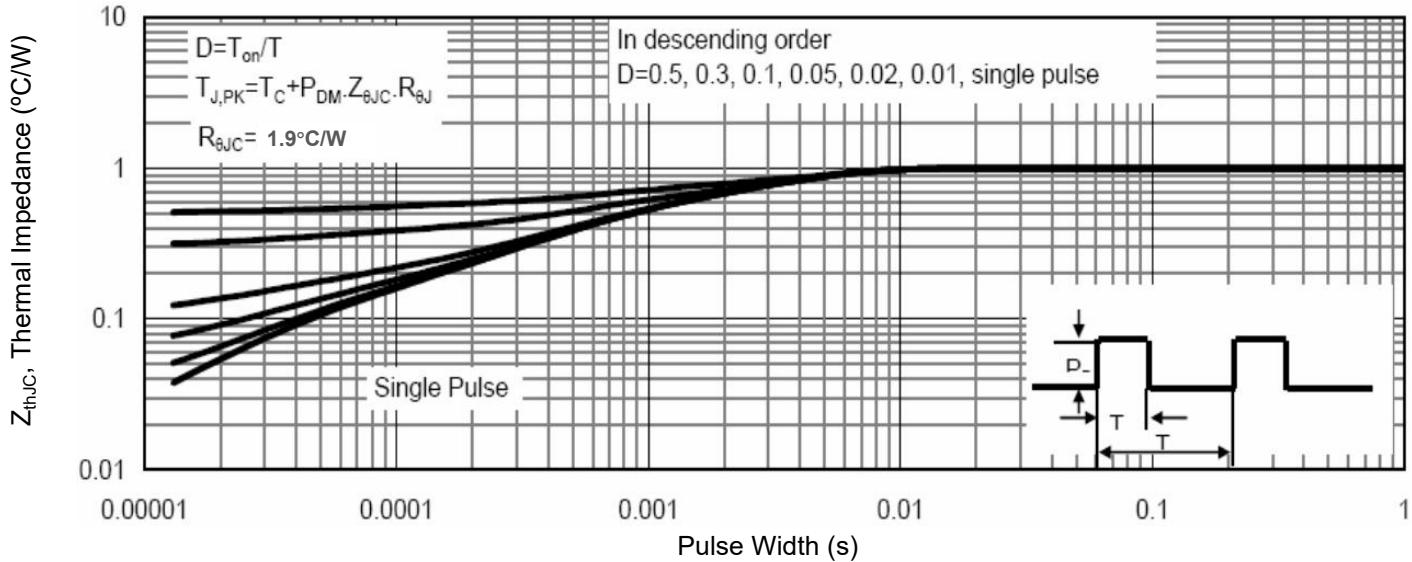


Figure 9. Normalized Maximum Transient Thermal Impedance



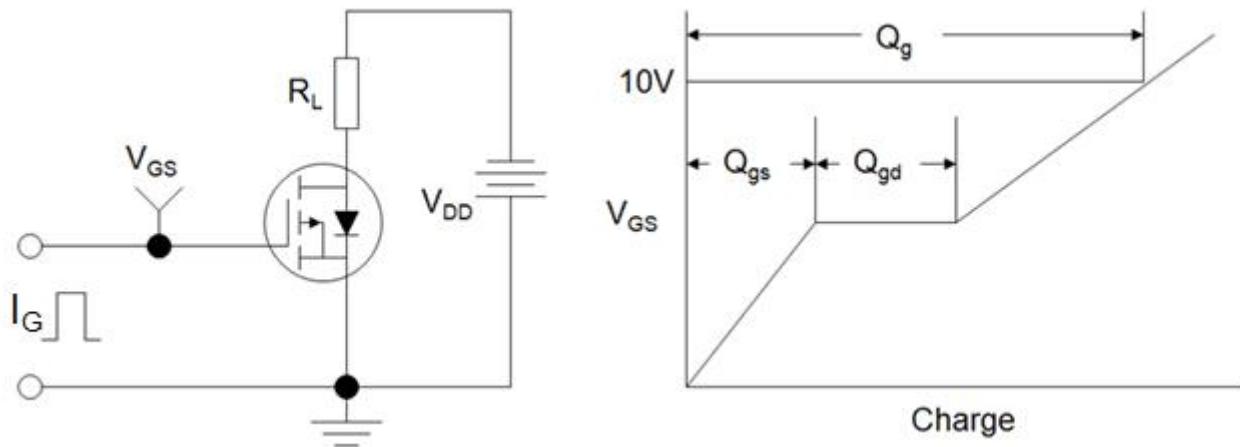
PMOS Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	-1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1	-1.6	-2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -10\text{A}$	--	13	16	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -8\text{A}$	--	18	20	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_D = -12\text{A}$	--	22	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -20\text{V}, f = 1.0\text{MHz}$	--	2451	--	pF
Output Capacitance	C_{oss}		--	224	--	
Reverse Transfer Capacitance	C_{rss}		--	213	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = -20\text{V}, I_D = -20\text{A}, V_{\text{GS}} = -10\text{V}$	--	45	--	nC
Gate-Source Charge	Q_{gs}		--	6.1	--	
Gate-Drain Charge	Q_{gd}		--	10.1	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -20\text{V}, I_D = -10\text{A}, R_G = 3\Omega$	--	9	--	ns
Turn-on Rise Time	t_r		--	7	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	78	--	
Turn-off Fall Time	t_f		--	39	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	-24	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = -10\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	-1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = -20\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = -100\text{A}/\mu\text{s}$	--	26	--	nC
Reverse Recovery Time	T_{rr}		--	29	--	ns

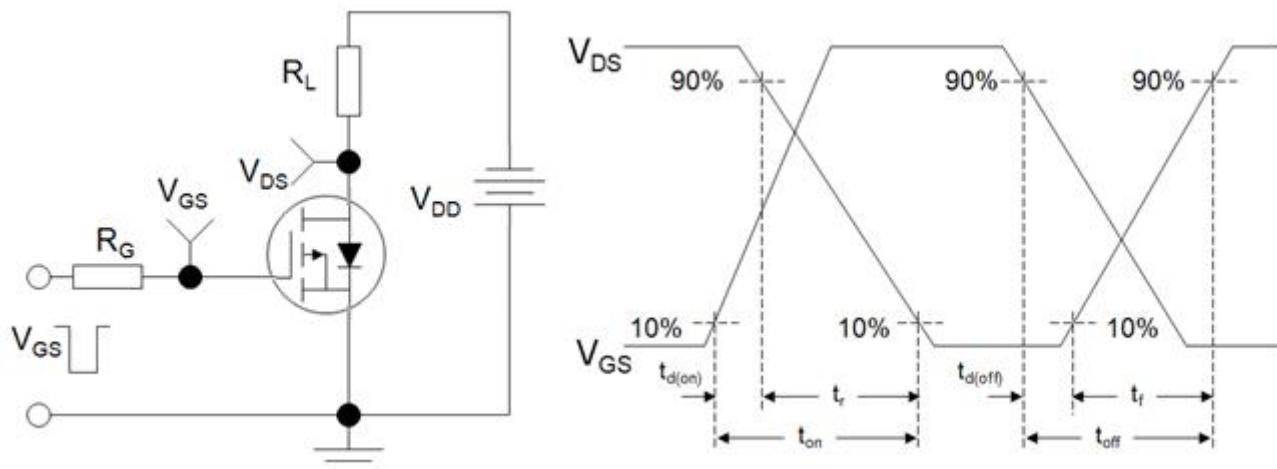
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=-40\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
3. Identical low side and high side switch with identical R_G

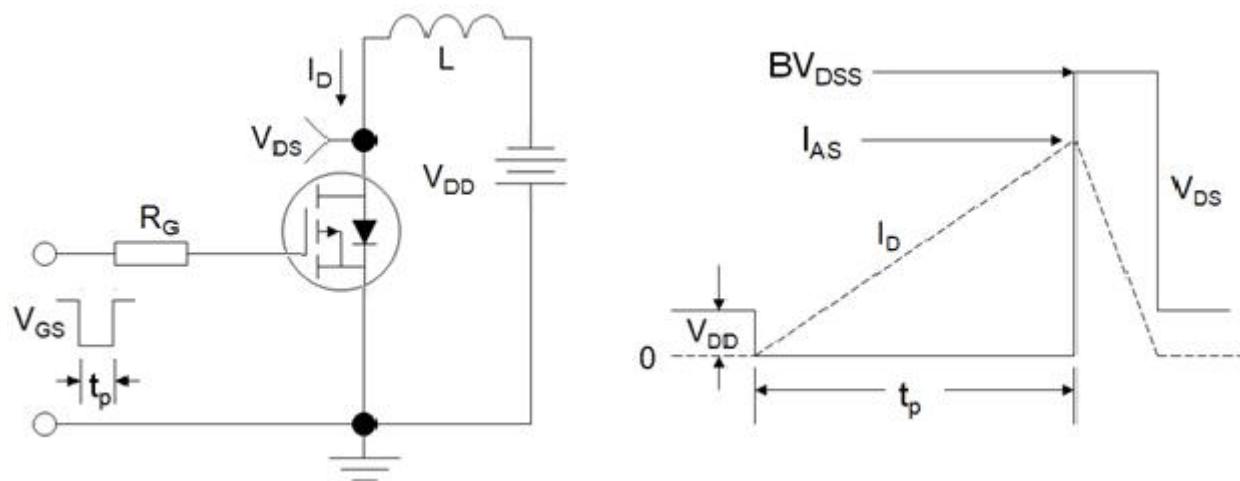
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



PMOS Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

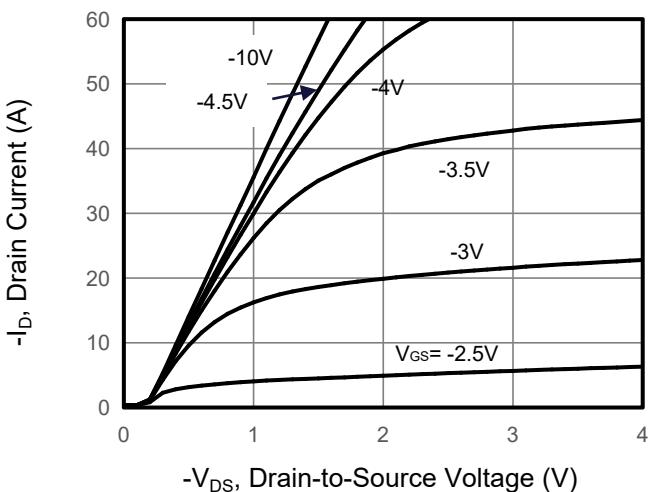


Figure 2. Transfer Characteristics

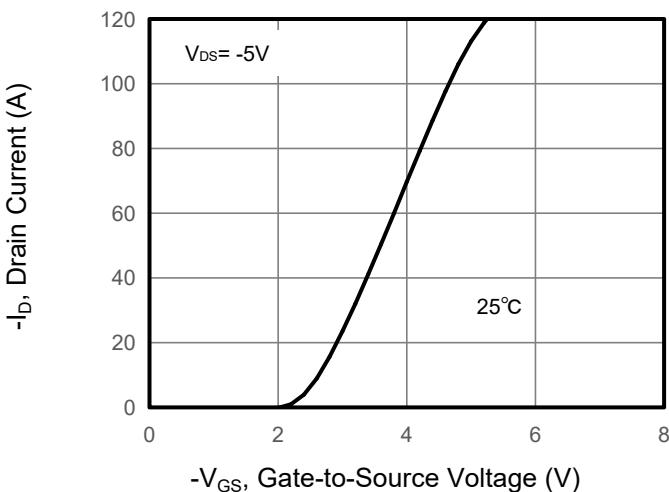


Figure 3. Drain Source On Resistance

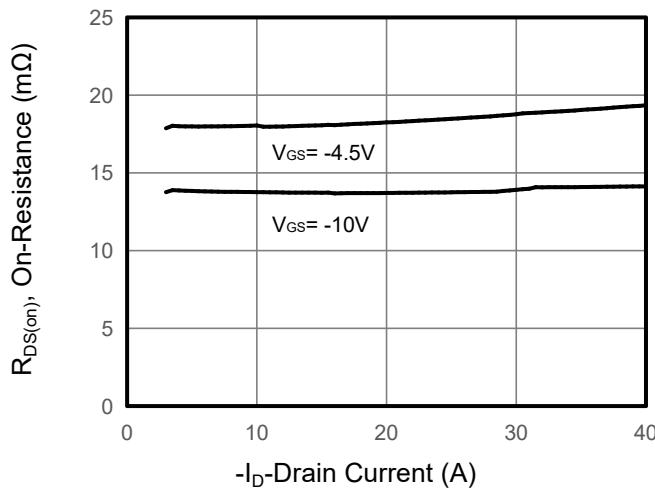


Figure 4. Gate Charge

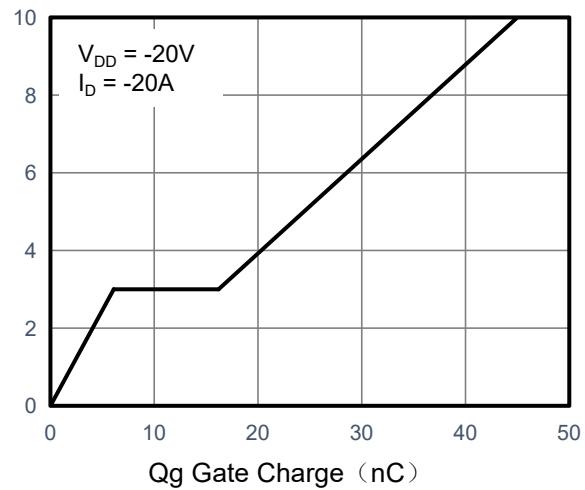


Figure 5. Capacitance

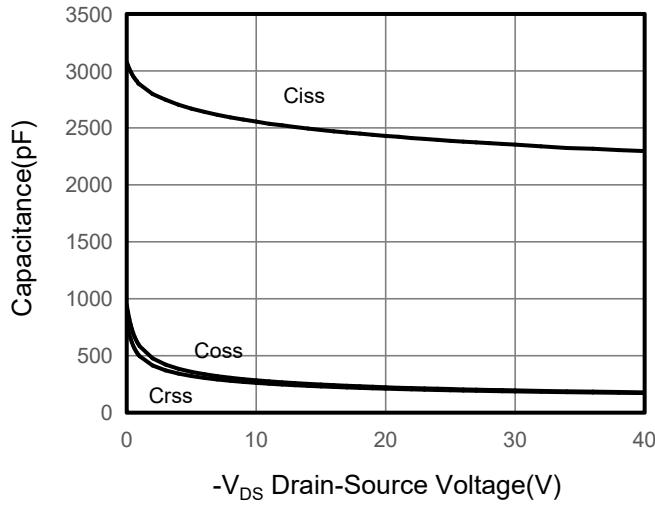
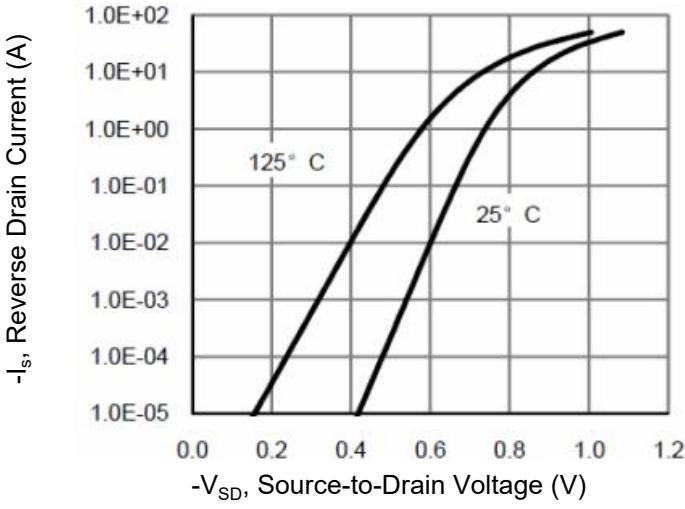


Figure 6. Source-Drain Diode Forward



PMOS Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

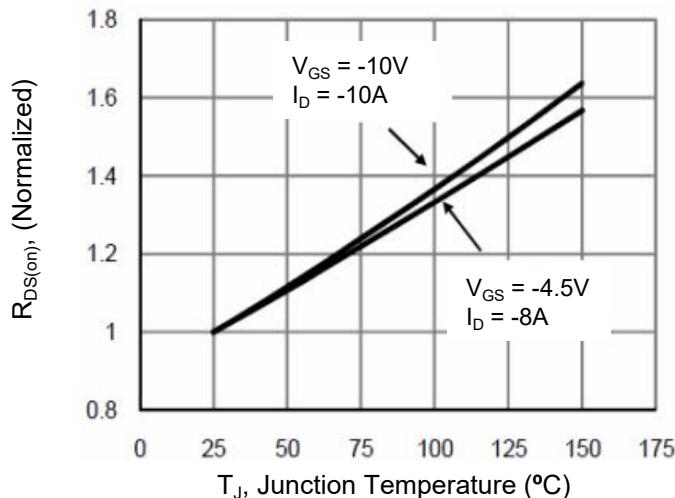


Figure 10. Safe Operation Area

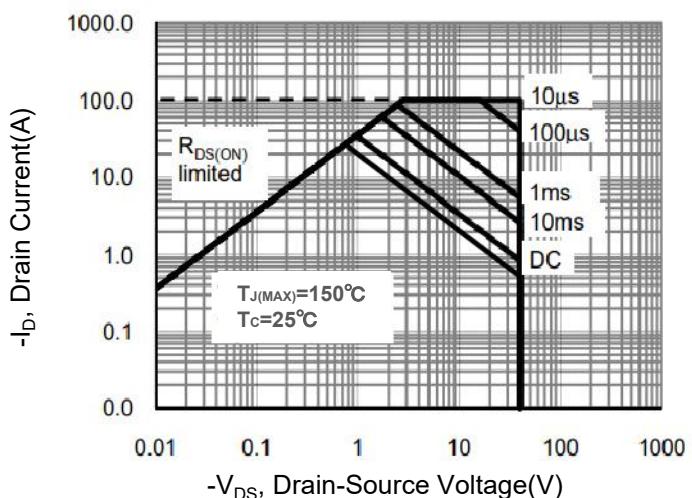
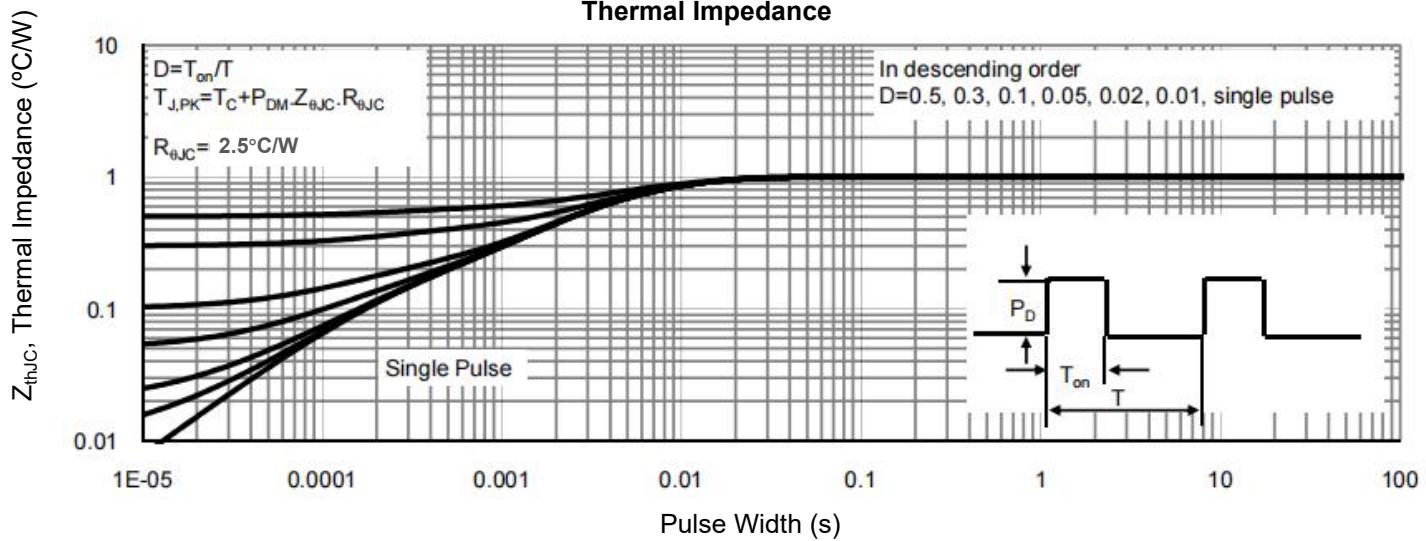
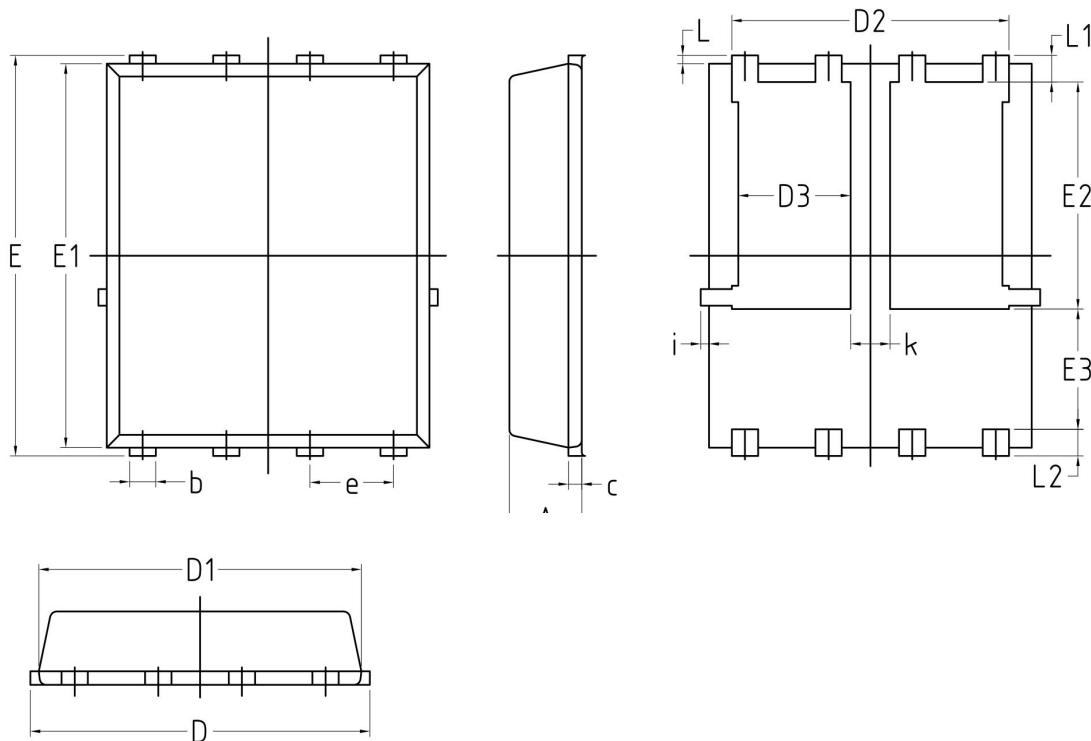


Figure 9. Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Dual Package Information



SYMBOL	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.203 BSC		0.0080 BSC	
D	4.80	5.40	0.1890	0.2126
D1	4.80	5.00	0.1890	0.1969
D2	4.11	4.31	0.1620	0.1700
D3	1.60	1.80	0.0629	0.0708
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	3.30	3.50	0.1300	0.1378
E3	1.70	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0019	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
i	/	0.18	/	0.0070
k	0.5	0.7	0.0197	0.0276

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